imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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BGA700L16 Low Noise Amplifier for IEEE 802.11a/b/g/n

THE BGA700L16 is a Wireless LAN dual band Low Noise Amplifier. The amplifier comprises a single stage amplifier for the 2.45 GHz band and a twostage amplifier to meet the requirements of the 4.9 to 5.95 GHz band. The complete circuitry, including a temperature stabilization block, fits on one die and needs no external matching elements.

One of the challenges of Wireless LAN application designers is to maximize network coverage and data throughput. The receiver system noise figure determines sensitivity, network coverage and data throughput.

The BGA700L16 uses a combination of Silicon Germanium Carbon epitaxy proprietary process and a low ohmic on chip ground contact from Infineon Technologies to deliver the word best-in class noise figure for wireless LAN systems.

The BGA700L16 ships as bare die or in a low profile Tiny Small Leadless Package code-named TSLP-16. The package dimensions are 2.3 x 2.3 x 0.39 mm³.

Product Brief



Applications

802.11a/b/g/n

Features

- Input/output 50 Ω matched internally
- SiGe:C process
- Shut down mode
- Temperature stabilization

Benefits

- Extended coverage
- Ultra-low noise figure
- Small form factor
- High level of integration
- Low cost

TSLP-16 Package

2.3 x 2.3 x 0.39 mm³



www.infineon.com/smallsignaldiscretes

Small Signal Discretes



Never stop thinking

Product Brief

Application Circuit



Performance					
Band [GHz]	Supply Voltage [V]	Supply Current [mA]	Gain [dB]	Noise Figure [dB]	Input P1dB [dB]
2.4	2.4 - 3.3	11	15	0.9	-10
5.6	2.4 - 3.3	17	21	1.3	-10



How to reach us: http://www.infineon.com

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Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest infineon Technologies Office.

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Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

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